

This invention relates to a photosensitive polyimide material having positive-type or negative-type photosensitivity, which may be developed with a high resolution with an irradiation energy having short wavelength such as ultraviolet light or electron beam. The positive-type photosensitive polyimide composition comprising a solvent-soluble polyimide which shows positive-type photosensitivity in the presence of a photoacid generator, which is obtained by polycondensation of at least one aliphatic tetracarboxylic dianhydride and/or alicyclic tetracarboxylic dianhydride and at least one aliphatic diamine and/or alicyclic diamine and/or diaminosiloxane; and the photoacid generator. Since the polyimide has negative-type photosensitivity when irradiated with electron beam in the absence of a photoacid generator, a method for forming negative-type polyimide pattern using the polyimide is also provided.